IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Type Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information					
upplier Informa	tion													
Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
onsemi											2024-04-29			
Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
Requester	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Date	Date Version Manufacturing Site			Weight*	UOM	Unit Type	
		NDSH25170A SiC JBS 1700V 25		5A TO247		2024-04-29 CPA		TPA		5321.033	mg	Each		
	roccess Informatio									1				
					-STD-020 MSI	_ Rating	Peak Process Body Temperature					r of Reflow Cyc	cles	
	(Sn) - annealed	C	U Alloy	<u> </u>	JA		0		C	30	secon	ids 3		
omments														
	**	•.•												
r more information	n regarding material cor	nposition p	olease refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die Attach Solder	23.353	mg	Supplier	Silver (Ag)	7440-22-4		0.5838	mg
			A	Lead (Pb)	7439-92-1	7a	21.6015	mg
			Supplier	Tin (Sn)	7440-31-5		1.1677	mg
Die SiC	32.0	mg	Supplier	Silicon Carbide	409-21-2		32	mg
Lead Frame	3488.88	mg	Supplier	Zinc (Zn)	7440-66-6		1.74	mg
			В	Nickel (Ni)	7440-02-0		113.9998	mg
			Supplier	Iron (Fe)	7439-89-6		2.09	mg
			Supplier	Copper (Cu)	7440-50-8		3369.9998	mg
			Supplier	Phosphorus (P)	7723-14-0		1.05	mg
Mold Compound-Black	1739.8	mg		Epoxy resin	proprietary data		104.388	mg
			Supplier	Phenolic Resin	Proprietary Data		104.388	mg
			Supplier	Carbon Black (C)	1333-86-4		8.699	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1478.8301	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		43.495	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg